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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

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KOHEI TAKEDA	09/27/2019
YUTA OATARI	09/27/2019
TAKASHI SHINJO	09/27/2019
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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16492361

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NAME OF SUBMITTER:	KELLY GREENE
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DATE SIGNED:	10/15/2019
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Total Attachments: 2

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> PATENT REEL: 050710 FRAME: 0874

Wenderoth, Lind & Ponack, LLP Attorney Docket No.: 2019-1557A

COMBINED DECLARATION AND ASSIGNMENT FOR UTILITY OR DESIGN APPLICATION		
Title of Invention	CURABLE RESIN COMPOSITION, CURED PRODUCT, ADHESIVE, BONDING FILM, COVERLAY FILM, FLEXIBLE COPPER-CLAD LAMINATE AND CIRCUIT BOARD	
1 1	DECLARATION	
As a below nai	ned inventor, I hereby declare that:	
This declaration is directed to:	The attached application, or	
	X United States application or PCT international application	
	number PCT/JP2018/002368 filed on January 26, 2018.	
The above-identified application was made or authorized to be made by me.		
I believe that I	am the original inventor or an original joint inventor of a claimed invention in the application.	
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.		
Note to Inventor: 37 C.F.R. § 1.63(c) states: "A person may not execute an oath or declaration for an application unless that person has reviewed and understands the contents of the application, including the claims, and is aware of the duty to disclose to the Office all information known to the person to be material to patentability as defined in § 1.56."		
	ASSIGNMENT	
In consideration	of the good and valuable consideration paid, I hereby sell and assign to	
SEKISIII CHI	EMICAL CO., LTD.	
(Name of As		
of 4-4, Nishite (address of A	mma 2-chome, Kita-ku, Osaka-shi, Osaka 530-0047, Japan Assignee)	
(hereinafter designated as the Assignee) my entire right, title and interest for the United States as defined in 35 USC 100, for any invention set forth in the above-identified application.		
and any continu	te all papers necessary in connection with this application for patent in the USPTO for the invention, ation, divisional or reissue applications thereof and also to execute separate assignments in connection ations as the Assignee may deem necessary or expedient.	
I agree to execute all papers necessary in connection with any post-grant proceeding which may occur in connection with this application or continuation, divisional or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such post-grant proceeding.		
The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements, which includes the right to claim priority and the right to be granted a patent in any PCT Contracting State.		

PATENT REEL: 050710 FRAME: 0875

I agree to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.				
I hereby authorize and request the USPTO to issue any and all Letters Patents of the United States resulting from the application or any continuation, divisional or reissue applications thereof to the Assignee, as Assignee of my entire interest, and covenant that I have not executed, and will not execute, any agreement in conflict herewith.				
First Inventor (Legal Name): Sayaka WAKIOKA				
Signature: Sayaka Watioka	SEP. 2 7. 2019			
Second Inventor (Legal Name): Kohel TAKEDA				
Signature: Koher TAKADA	Date: SEP. 2.7, 2019			
Third Inventor (Legal Name): Yuta OATARI				
Signature: Yu ta OATAR I	Date: SEP. 2 7. 2019			
Fourth Inventor (Legal Name): <u>Takashi SHINJO</u>				
Signature: Takashi SHINJO	Date: SEP. 2 7. 2019			
Fifth Inventor (Legal Name): Masami SHINDO				
Signature: Masami SHINDO	SEP. 2 7. 2019			